

# MC74HC112A

## Dual J-K Flip-Flop with Set and Reset

### High-Performance Silicon-Gate CMOS

The MC74HC112A is identical in pinout to the LS112. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

Each flip-flop is negative-edge clocked and has active-low asynchronous Set and Reset inputs.

The HC112A is identical in function to the HC76, but has a different pinout.

#### Features

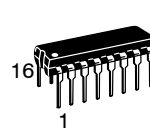
- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0  $\mu$ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Similar in Function to the LS112 Except When Set and Reset are Low Simultaneously
- Chip Complexity: 100 FETs or 25 Equivalent Gates
- Pb-Free Packages are Available\*



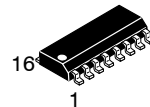
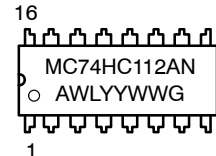
ON Semiconductor®

<http://onsemi.com>

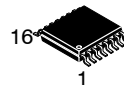
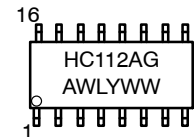
#### MARKING DIAGRAMS



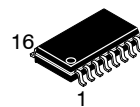
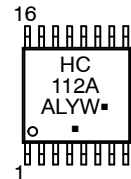
PDIP-16  
N SUFFIX  
CASE 648



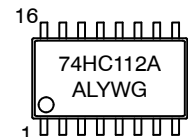
SOIC-16  
D SUFFIX  
CASE 751B



TSSOP-16  
DT SUFFIX  
CASE 948F



SOEIAJ-16  
F SUFFIX  
CASE 966



A = Assembly Location  
L, WL = Wafer Lot  
Y, YY = Year  
W, WW = Work Week  
G = Pb-Free Package  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74HC112A

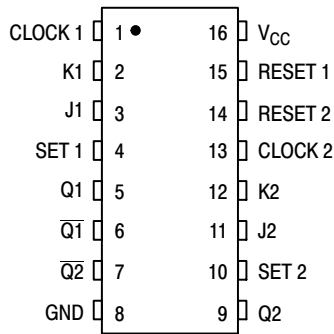


Figure 1. Pin Assignment

## FUNCTION TABLE

Inputs					Outputs	
Set	Reset	Clock	J	K	Q	Q̄
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	L*	L*
H	H	~	L	L	No Change	
H	H	~	L	H	L	H
H	H	~	H	L	H	L
H	H	~	H	H	Toggle	
H	H	L	X	X	No Change	
H	H	H	X	X	No Change	
H	H	~	X	X	No Change	

\*Both outputs will remain low as long as Set and Reset are low, but the output states are unpredictable if Set and Reset go high simultaneously.

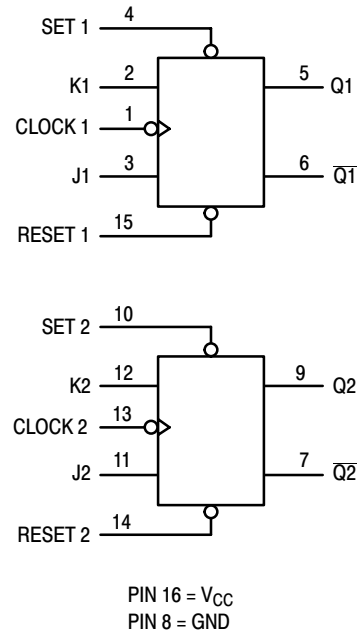


Figure 2. Logic Diagram

## ORDERING INFORMATION

Device	Package	Shipping†
MC74HC112ANG	PDIP-16 (Pb-Free)	500 Units / Rail
MC74HC112ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC112ADR2G	SOIC-16 (Pb-Free)	2500 Units / Reel
MC74HC112ADTR2G	TSSOP-16*	2500 Units / Reel
MC74HC112AFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb-Free.

# MC74HC112A

## MAXIMUM RATINGS\*

Symbol	Parameter	Value	Unit	
$V_{CC}$	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V	
$V_{in}$	DC Input Voltage (Referenced to GND)	- 1.5 to $V_{CC} + 1.5$	V	
$V_{out}$	DC Output Voltage (Referenced to GND)	- 0.5 to $V_{CC} + 0.5$	V	
$I_{in}$	DC Input Current, per Pin	$\pm 20$	mA	
$I_{out}$	DC Output Current, per Pin	$\pm 25$	mA	
$I_{CC}$	DC Supply Current, $V_{CC}$ and GND Pins	$\pm 50$	mA	
$P_D$	Power Dissipation in Still Air	Plastic DIP† SOIC Package† TSSOP Package†	750 500 450	mW
$T_{stg}$	Storage Temperature	- 65 to + 150	°C	
$T_L$	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP, SOIC or TSSOP)	260	°C	

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $GND \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$ . Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

\*Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

†Derating — Plastic DIP: - 10 mW/°C from 65° to 125°C  
SOIC Package: - 7 mW/°C from 65° to 125°C  
TSSOP Package: - 6.1 mW/°C from 65° to 125°C

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
$V_{CC}$	DC Supply Voltage (Referenced to GND)	2.0	6.0	V	
$V_{in}, V_{out}$	DC Input Voltage, Output Voltage (Referenced to GND)	0	$V_{CC}$	V	
$T_A$	Operating Temperature, All Package Types	- 55	+ 125	°C	
$t_r, t_f$	Input Rise and Fall Time (Figure 1)	$V_{CC} = 2.0 \text{ V}$ $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$	0 0 0	1000 500 400	ns

## DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	$V_{CC}$ V	Guaranteed Limit			Unit
				- 55 to 25°C	$\leq 85^\circ\text{C}$	$\leq 125^\circ\text{C}$	
$V_{IH}$	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out}  \leq 20 \mu\text{A}$	2.0	1.5	1.5	1.5	V
			4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
$V_{IL}$	Maximum Low-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out}  \leq 20 \mu\text{A}$	2.0	0.3	0.3	0.3	V
			4.5	0.9	0.9	0.9	
			6.0	1.2	1.2	1.2	
$V_{OH}$	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \leq 20 \mu\text{A}$	2.0	1.9	1.9	1.9	V
			4.5	4.4	4.4	4.4	
		$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \leq 4.0 \text{ mA}$ $ I_{out}  \leq 5.2 \text{ mA}$	4.5	3.98	3.84	3.70	
			6.0	5.48	5.34	5.20	
$V_{OL}$	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \leq 20 \mu\text{A}$	2.0	0.1	0.1	0.1	V
			4.5	0.1	0.1	0.1	
		$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \leq 4.0 \text{ mA}$ $ I_{out}  \leq 5.2 \text{ mA}$	4.5	0.26	0.33	0.40	
			6.0	0.26	0.33	0.40	
$I_{in}$	Maximum Input Leakage Current	$V_{in} = V_{CC} \text{ or GND}$	6.0	$\pm 0.1$	$\pm 1.0$	$\pm 1.0$	$\mu\text{A}$
$I_{CC}$	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC} \text{ or GND}$ $I_{out} = 0 \mu\text{A}$	6.0	4	40	80	$\mu\text{A}$

# MC74HC112A

## AC ELECTRICAL CHARACTERISTICS ( $C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Symbol	Parameter	V <sub>CC</sub> V	Guaranteed Limit			Unit
			- 55 to 25°C	≤ 85°C	≤ 125°C	
f <sub>max</sub>	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 4)	2.0	6.0	4.8	4.0	MHz
		4.5	30	24	20	
		6.0	35	28	24	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Clock to Q or $\bar{Q}$ (Figures 1 and 4)	2.0	125	155	190	ns
		4.5	25	31	38	
		6.0	21	26	32	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Reset to Q or $\bar{Q}$ (Figures 2 and 4)	2.0	155	195	235	ns
		4.5	31	39	47	
		6.0	26	33	40	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Set to Q or $\bar{Q}$ (Figures 2 and 4)	2.0	165	205	250	ns
		4.5	33	41	50	
		6.0	28	35	43	
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 1 and 4)	2.0	75	95	110	ns
		4.5	15	19	22	
		6.0	13	16	19	
C <sub>in</sub>	Maximum Input Capacitance	—	10	10	10	pF

C <sub>PD</sub>	Power Dissipation Capacitance (Per Flip-Flop)*	Typical @ 25°C, V <sub>CC</sub> = 5.0 V			pF
		35			

\* Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

## TIMING REQUIREMENTS (Input $t_r = t_f = 6$ ns)

Symbol	Parameter	V <sub>CC</sub> V	Guaranteed Limit			Unit
			- 55 to 25°C	≤ 85°C	≤ 125°C	
t <sub>su</sub>	Minimum Setup Time, J or K to Clock (Figure 3)	2.0	100	125	150	ns
		4.5	20	25	30	
		6.0	17	21	26	
t <sub>h</sub>	Minimum Hold Time, Clock to J or K (Figure 3)	2.0	3	3	3	ns
		4.5	3	3	3	
		6.0	3	3	3	
t <sub>rec</sub>	Minimum Recovery Time, Set or Reset Inactive to Clock (Figure 2)	2.0	100	125	150	ns
		4.5	20	25	30	
		6.0	17	21	26	
t <sub>w</sub>	Minimum Pulse Width, Clock (Figure 1)	2.0	80	100	120	ns
		4.5	16	20	24	
		6.0	14	17	20	
t <sub>w</sub>	Minimum Pulse Width, Set or Reset (Figure 2)	2.0	80	100	120	ns
		4.5	16	20	24	
		6.0	14	17	20	
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times (Figure 1)	2.0	1000	1000	1000	ns
		4.5	500	500	500	
		6.0	400	400	400	

# MC74HC112A

## SWITCHING WAVEFORMS

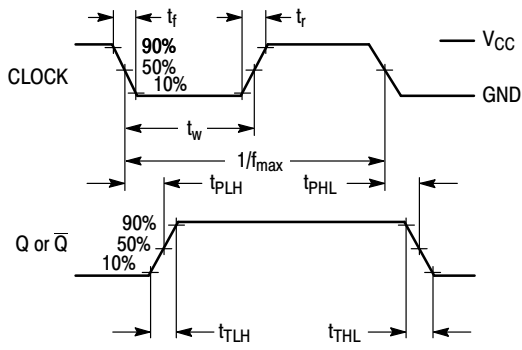


Figure 1.

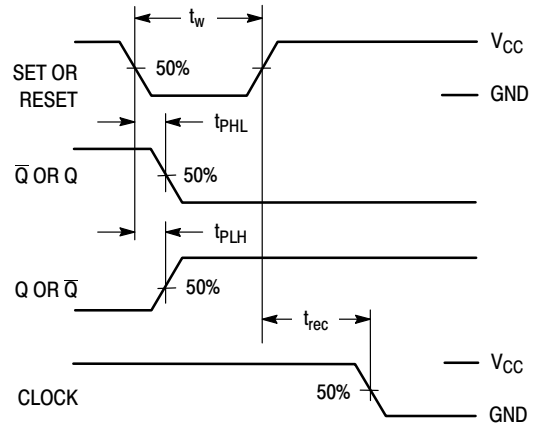


Figure 2.

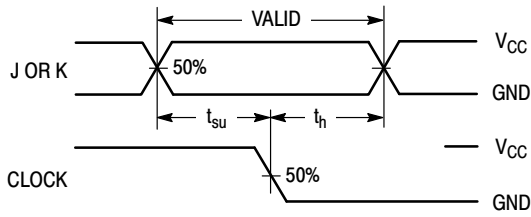
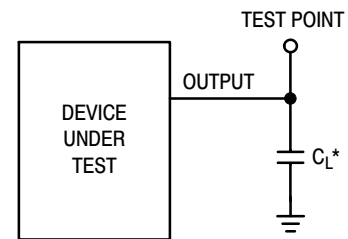


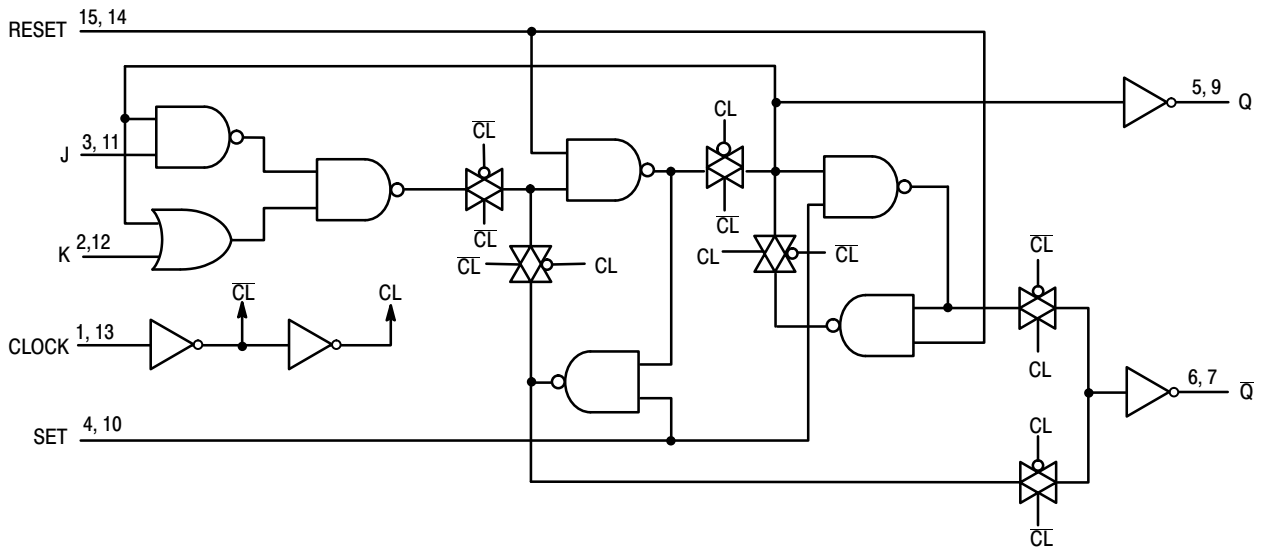
Figure 3.



\*Includes all probe and jig capacitance

Figure 4. Test Circuit

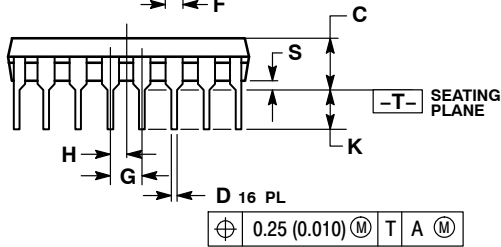
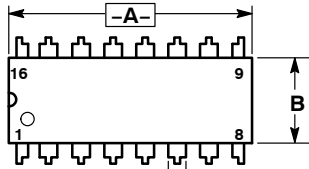
## EXPANDED LOGIC DIAGRAM



# MC74HC112A

## PACKAGE DIMENSIONS

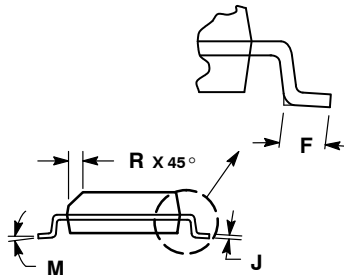
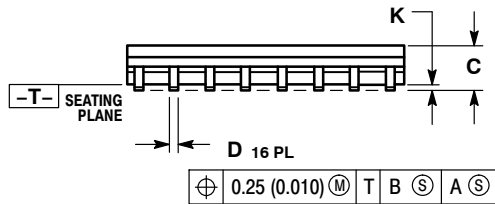
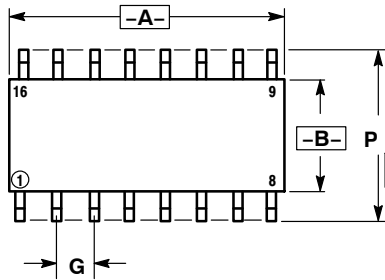
### PDIP-16 N SUFFIX CASE 648-08 ISSUE T



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

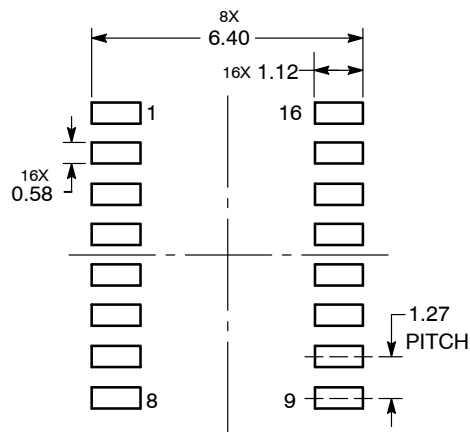
### SOIC-16 D SUFFIX CASE 751B-05 ISSUE K



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

### SOLDERING FOOTPRINT

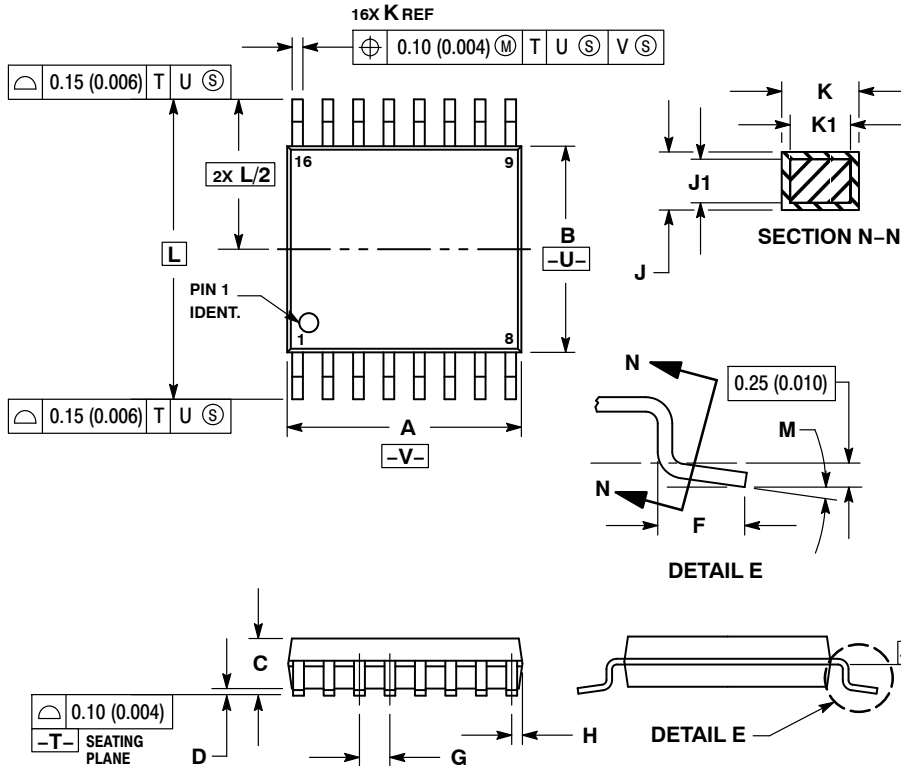


DIMENSIONS: MILLIMETERS

# MC74HC112A

## PACKAGE DIMENSIONS

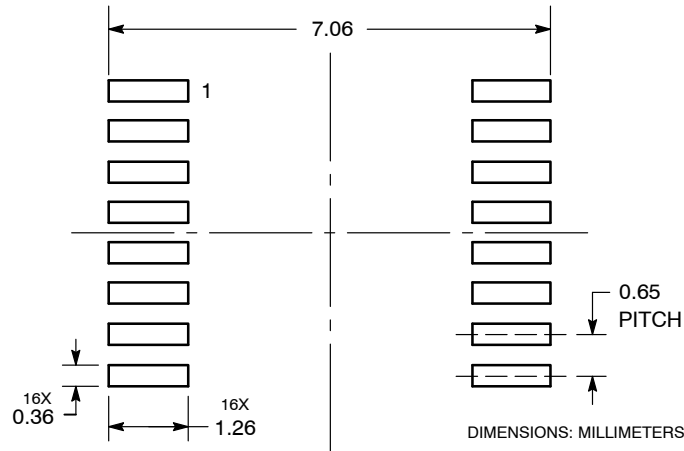
TSSOP-16  
DT SUFFIX  
CASE 948F-01  
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

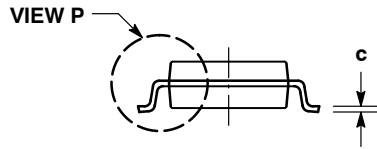
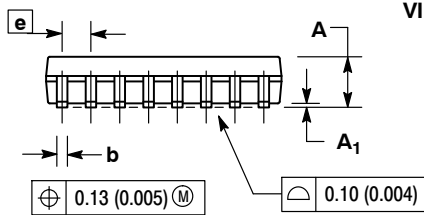
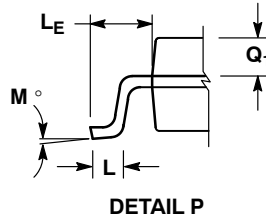
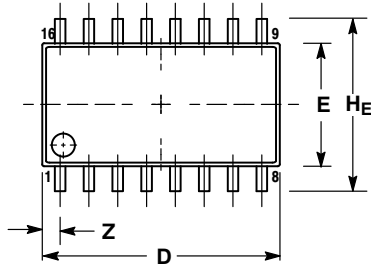
### SOLDERING FOOTPRINT



# MC74HC112A

## PACKAGE DIMENSIONS

SOEIAJ-16  
F SUFFIX  
CASE 966-01  
ISSUE A



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H <sub>E</sub>	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L <sub>E</sub>	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### PUBLICATION ORDERING INFORMATION

**LITERATURE FULFILLMENT:**  
Literature Distribution Center for ON Semiconductor  
P.O. Box 5163, Denver, Colorado 80217 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** orderlit@onsemi.com

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada  
**Europe, Middle East and Africa Technical Support:**  
Phone: 421 33 790 2910  
**Japan Customer Focus Center**  
Phone: 81-3-5773-3850

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)  
**Order Literature:** <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative





## Стандарт Электрон Связь

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

### Наши контакты:

**Телефон:** +7 812 627 14 35

**Электронная почта:** [sales@st-electron.ru](mailto:sales@st-electron.ru)

**Адрес:** 198099, Санкт-Петербург,  
Промышленная ул, дом № 19, литера Н,  
помещение 100-Н Офис 331